Docket No.:M4065.0319/P319-A (PATENT)

Examiner: Erik J. Kielin

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Ronald A. Weimer, et al.

Application No.: 09/912,558

Filed: July 26, 2001

For: FABRICATION OF DRAM AND OTHER SEMICONDUCTOR DEVICES WITH AN INSULATING FILM USING A WET RAPID THERMAL OXIDATION PROCESS

Group Art Unit: 2813

AMENDMENT

BOX: Non-Fee Amendment Commissioner for Patents Washington, DC 20231

Dear Sir:

This paper is in response to the Office Action dated October 7, 2002 rejecting claims 13, 14, 16, 17, and 41-42, please amend the above-captioned U.S. Patent application as follows:

In the Claims:

Please rewrite claim 41 as follows:

41. (twice amended) A method of fabricating a semiconductor device, the method comprising:

depositing a dielectric film with a thickness greater than about 40 Angstroms over a semiconductor substrate; and

subjecting the dielectric film to a wet oxidation with steam in a rapid thermal

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